BD17002020

O'AGANO.					
Registration No:					

Total Number of Pages : 02 M.TECH

AR-17

M.TECH 1ST SEMESTER EXAMINATIONS(BACK), NOV/DEC 2019 PE, MPEPE1044

ADVANCED POWER SEMICONDUCTOR DEVICES

Time: 3 Hours Max Marks: 70

The figures in the right hand margin indicate marks.

PART-A

(10 X 2=20 MARKS)

- 1. Answer the following questions.
 - a. Distinguish between Power and Linear diodes
 - b. Define safe operating area
 - c. How is secondary breakdown avoided in BJT
 - d. What are current controlled devices? Mention its applications
 - e. What are the limitations of MOSFET? How does single electron theory overcome this limitations
 - f. Compare RCT and FCT
 - g. Draw the Gate driver circuit of BJT
 - h. What is the need of isolation for power semiconductor devices
 - i. Mention any 4 types of heat sinks suitable for semiconductor devices
 - j. What are the parameters to be considered for proper mounting of the device with heat sink

PART-B

(5 X 10=50 MARKS)

Answer any five questions from the following.

O2.

- a. What are the different types of power diodes? Explain
- b. Explain the EMI phenomenon due to switching. What are the different methods to reduce it? O3.
- a. Explain the two transistor transient model of a thyristor
- b. Explain the Negative Temperature Coefficient and Secondary Breakdown of BJT O4
- a. Explain the construction of a power MOSFET.
- b. Draw and explain the static and switching characteristics of power MOSFET O5.
- a. Write a brief note on driver circuit of SCR.
- b. Explain the necessity of using isolation, pulse transformer as protection circuits Q6.
- a) With the help of neat sketch, explain the electrical equivalent circuit of thermal model of a

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power device.

b) Explain about heat sink consider an aluminium rod with measurement height, h=1cm, Breadth=1cm and length=20cm. The rate of heat energy entering at the left end (where the temperature is T_2) is 3W and the temperature at the right surface is T_1 =40°C. Find T_2 . (Thermal conductivity λ =200w-m⁻¹0c⁻¹)

Q 7.

- a. Distinguish controlled and un-controlled devices.
- b. Analyze V-I characteristics of various real switching devices Q8.
- a. Differentiate between GTO and SCR
- b) A thyristor is fed from a constant DC voltage of 240Volts and connected to a resistive load of Rl=50 ohms. The specified limits for di/dt=60 amp/micro sec and dv/dt = 300v/micro sec.Determine the value of di/dt inductance and snubber circuit parameters. Assume damping ratio =0.5

